

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : Unassigned
Applicant : Carapella, et al.
Filed : 09/08/2003
Title : METHODS OF SPLIT CAVITY WALL PLATING FOR
AN INTEGRATED CIRCUIT PACKAGE (As Amended)

Docket No. : 42P6139CD
Customer No. : 8791

Which is a Divisional of:

Appl. No. : 09/665,034
Applicant : Carapella, et al.
Filed : 09/19/2000
Title : METHODS FORMING AN INTEGRATED CIRCUIT
PACKAGE WITH A SPLIT WALL (As Amended)
TC/A.U. : 3729
Examiner : Chang, Rick Kiltae

Which is a Continuation of:

Appl. No. : 09/153,630
Applicant : Carapella, et al.
Filed : 09/15/1998
Title : SPLIT CAVITY WALL PLATING FOR AN
INTEGRATED CIRCUIT PACKAGE

PRELIMINARY AMENDMENT ACCOMPANYING
35 USC 120 and 37 CFR 1.53(b)(1) DIVISIONAL APPLICATION

Mail Stop New Application
Commissioner for Patents
Alexandria, VA 22313

Dear Sir:

Prior to a first examination in the 35 USC 120 and 37 CFR 1.53(b)(1) divisional application filed herewith, please enter the following amendments:

Title Amendments begin on page 2.
Specification Amendments begin on page 3.
Drawing Amendments begin on page 6.
Claim Amendments begin on page 7.
Remarks begin on page 15.
Conclusion with signature is on page 21.

IN THE TITLE

Please amend the Title of the Application as follows:

"METHODS OF SPLIT CAVITY WALL PLATING FOR AN INTEGRATED
CIRCUIT PACKAGE".